

SOT1970-1

SIL2, single in-line package, 2 terminals, 4.0 mm pitch, 6.9 mm x 8.9 mm x 3.3 mm body

6 May 2021

Package information

1 Package summary

Terminal position code	S (single)
Package type descriptive code	SIL2
Package style descriptive code	SIP (single in-line package)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	04-05-2021
Manufacturer package code	98ASA01520D

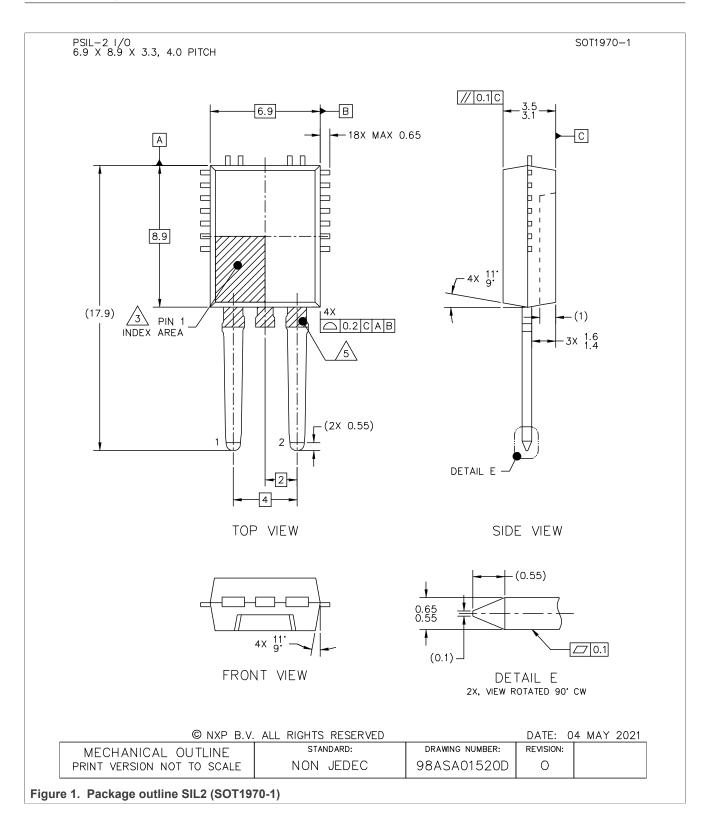
Table 1. Package summary

Parameter	Min	Nom	Мах	Unit
package length	6.7	6.9	7.1	mm
package width	8.7	8.9	9.1	mm
seated height	3.1	3.3	3.5	mm
nominal pitch	-	4	-	mm
actual quantity of termination	-	2	-	



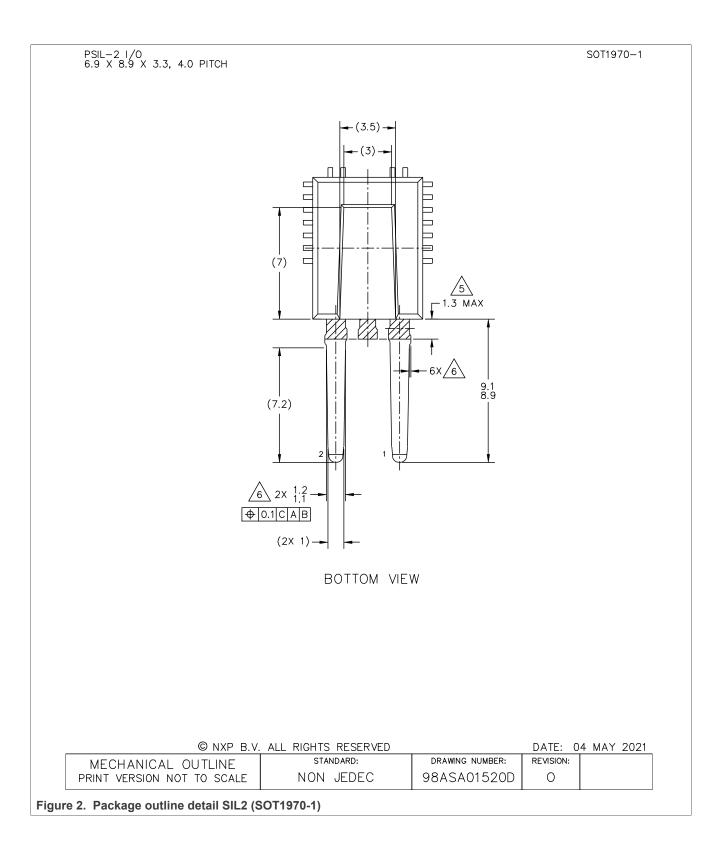
SIL2, single in-line package, 2 terminals, 4.0 mm pitch, 6.9 mm x 8.9 mm x 3.3 mm body

Package outline 2



SOT1970-1

SIL2, single in-line package, 2 terminals, 4.0 mm pitch, 6.9 mm x 8.9 mm x 3.3 mm body



SOT1970-1

SIL2, single in-line package, 2 terminals, 4.0 mm pitch, 6.9 mm x 8.9 mm x 3.3 mm body

PSIL-2 1/0 6.9 X 8.9 X 3.3, 4.0 PITCH			SOT1970-1
NOTES:			
1. ALL DIMENSIONS ARE IN MILLIN	IETER.		
2. DIMENSIONING AND TOLERANCI	NG AS PER ASME Y14.5M	-1994.	
3. PIN 1 FEATURE SHAPE, SIZE	AND LOCATION MAY VARY.		
 PACKAGE BODY SIZE DOES NO PER SIDE. THESE DIMENSIONS BODY. 			
5. HATCED AREA REPRESENT ALL	OWABLE MOLD FLASH OF	1.3 MAX.	
6. LEAD SHOULDER DOES NOT IN			
SHALL BE 0.15 TOTAL IN EXCE	ESS OF THE LEAD SHOULD	DER AT MAXIMUM MATER	RIAL CONDITION.
	ALL RIGHTS RESERVED STANDARD:	DRAWING NUMBER:	DATE: 04 MAY 20 REVISION:
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	NON JEDEC	98ASA01520D	O O
3. Package outline note SIL2 (SO	1970-1)		

SIL2, single in-line package, 2 terminals, 4.0 mm pitch, 6.9 mm x 8.9 mm x 3.3 mm body

3 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

SIL2, single in-line package, 2 terminals, 4.0 mm pitch, 6.9 mm x 8.9 mm x 3.3 mm body

Contents

1	Package summary	1
2	Package outline	2
3	Legal information	5

© NXP B.V. 2021.

For more information, please visit: http://www.nxp.com For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 6 May 2021